

WHAT IS CLAIMED IS:

1. A semiconductor dynamic sensor which is sucked and transported by a collet chuck, comprising:

a semiconductor substrate;

5 a displacement portion formed in the semiconductor substrate, the displacement portion having beam structure and displaceable in response to applied dynamic force; and

a suction portion which is formed on the surface of the semiconductor substrate in a region separated from the displacement
10 portion, the suction portion being a flat portion whose area is larger than a contact area of a tip of the collet chuck.

2. The semiconductor dynamic sensor according to claim 1, wherein the suction portions is formed at a plurality of locations
15 on the surface of the semiconductor substrate.

3. The semiconductor dynamic sensor according to claim 2, wherein the suction portion is formed at each corner of the semiconductor substrate.

20 4. The semiconductor dynamic sensor according to claim 1, wherein the suction portion has no step portion and no wiring pattern.

25 5. A method of transporting the semiconductor dynamic sensor according to claim 1, comprising a step of sucking the suction portion by using the collet chuck.

6. A semiconductor dynamic sensor which is sucked and transported by a collet chuck, comprising:

a semiconductor substrate;

5 a fixed electrode formed in the semiconductor substrate, the fixed electrode having beam structure;

a movable electrode formed in the semiconductor substrate and movable in response to applied dynamic force, the movable electrode having beam structure and separated from the fixed
10 electrode by a clearance; and

a suction portion which is formed on the surface of the semiconductor substrate in a region where air is not sucked from the clearance between the fixed electrode and the movable electrode when the collet chuck sucks the semiconductor dynamic sensor, the
15 suction portion being flat portion whose area is larger than a contact area of a tip of the collet chuck.